

INFORMATION ABOUT THE FINAL EXAM**Office Hours During RRR and Finals Week:**

During the RRR week, your TA's will continue to hold office hours during the regular times and in the regular locations. Prof. Nguyen will be in Washington, DC, for the IEEE International Electron Devices Meeting and other meetings, so will not hold office hours during RRR week.

During finals week, office hours and related study events will be concentrated on the Monday before the exam, and will be as follows:

Monday: 10-12 a.m.	Brian Pepin
Monday: 2-4 p.m.	Henry Barrow
Monday: 6-8 p.m.	Review Session

Date of Exam:

Exam Group 5: Tuesday, Dec. 13, 8-11 a.m. (sharp)

Place:

289 Cory (i.e., our regular room)

General Information:

The exam will be open book and open notes. Bring a calculator to the exam. (You will not be allowed to use a computer or smart phone.) You will be provided with exam sheets with enough space to put all your work on these sheets. You should show and include all your work on the exam sheets. The exam will consist of a few problems, each with a number of parts.

Material to be Covered:

Reading in Senturia, class lecture notes, handouts, and homeworks. The exam is meant to include all material covered in the class, with stronger emphasis on material covered after the Midterm Exam. A summary of important topics that might be covered on the Final Exam can be listed as follows:

1. Basic MEMS fabrication process modules, including oxidation, film deposition, lithography, etching, ion implantation, and diffusion. You should especially have a good understanding of MEMS-centric etching and what influences selectivity and the degree of anisotropy.
2. Physics of stiction and bending/warping due to residual or thermal stresses and other phenomena. Be able to quantitatively determine whether a particular structure is warped or stuck down.
3. MEMS process flow design and layout. Be prepared to design your own process flow and layout for some arbitrary cross-section or 3D structure.
4. Surface micromachining, including its basic process flow, release issues (e.g., stiction), material choices, residual stress, stringers and methods for eliminating them.

5. Mechanics of materials for MEMS, including stress, strain, material properties, and on-chip measurement & characterization of mechanical properties.
6. Microstructural elements, including bending moment and strain, flexural rigidity, residual stress analysis, boundary conditions, and spring combinations. You should be familiar with beam bending equations and their application. You should also be able to derive properties for arbitrary connections of beams (i.e., springs).
7. Pros and cons of scaling, including understanding of thermal circuits and impact of scaling on surface-to-volume ratios.
8. Energy methods for determination of deflection functions and resonance frequencies.
9. Input/output transducer modeling, including energy methods and construction of equivalent circuits. Here, you should understand first and second order effects for both parallel-plate and comb-capacitive transducers, including electrical stiffness and levitation.
10. Micromechanical circuit analysis, including specification of the equivalent circuit for a micromechanical device with multiple ports and determination of the output variables (e.g., current, voltage, displacement, velocity) at the various ports when emplaced into a circuit of other elements (e.g., resistors, capacitors, etc.).
11. Sensing circuits, including topologies that minimize parasitics. Be able to analyze circuit topologies and make the right choice of which circuit to use to grab a desired output variable.
12. Gyroscope operation and scale factor. Be able to determine how scale factor changes with changes in a given environmental variable.

Practice Material:

To give you some semblance of what to expect, the solutions to the Final Exams given over the last three years are provided with this document. Note that the material coverage between previous years and this year differ slightly (e.g., some things were emphasized more than others), so might not be fully representative of what your exam might look like. However, it still gives you some sample problems on which to practice. And as always, practice is one of the best ways to do well on an engineering exam. In fact, a good way to study for this exam is to make up some of your own problems and solve them.